

版本	修订日期	有修订的页码	修订涉及的内容	拟制	审核
A	2020-6-24			谢小倩	刘晓荣
B	2020-7-9				

/ Descriptions

SOT-363 塑封封装肖特基二极管。
Schottky Diode in a SOT-363 Plastic Package.

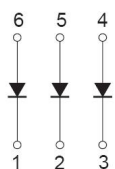
/ Features

低正向压降，可忽略的反向恢复时间。无卤产品。
Low positive pressure drop, can ignore the reverse recovery time. HF Product.

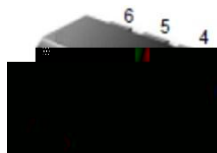
/ Applications

肖特基二极管。
Schottky diode.

/ Equivalent Circuit



/ Pinning



PIN: See Equivalent Circuit.

/ h_{FE} Classifications & Marking

Model	SD103ATW
Marking	KLL

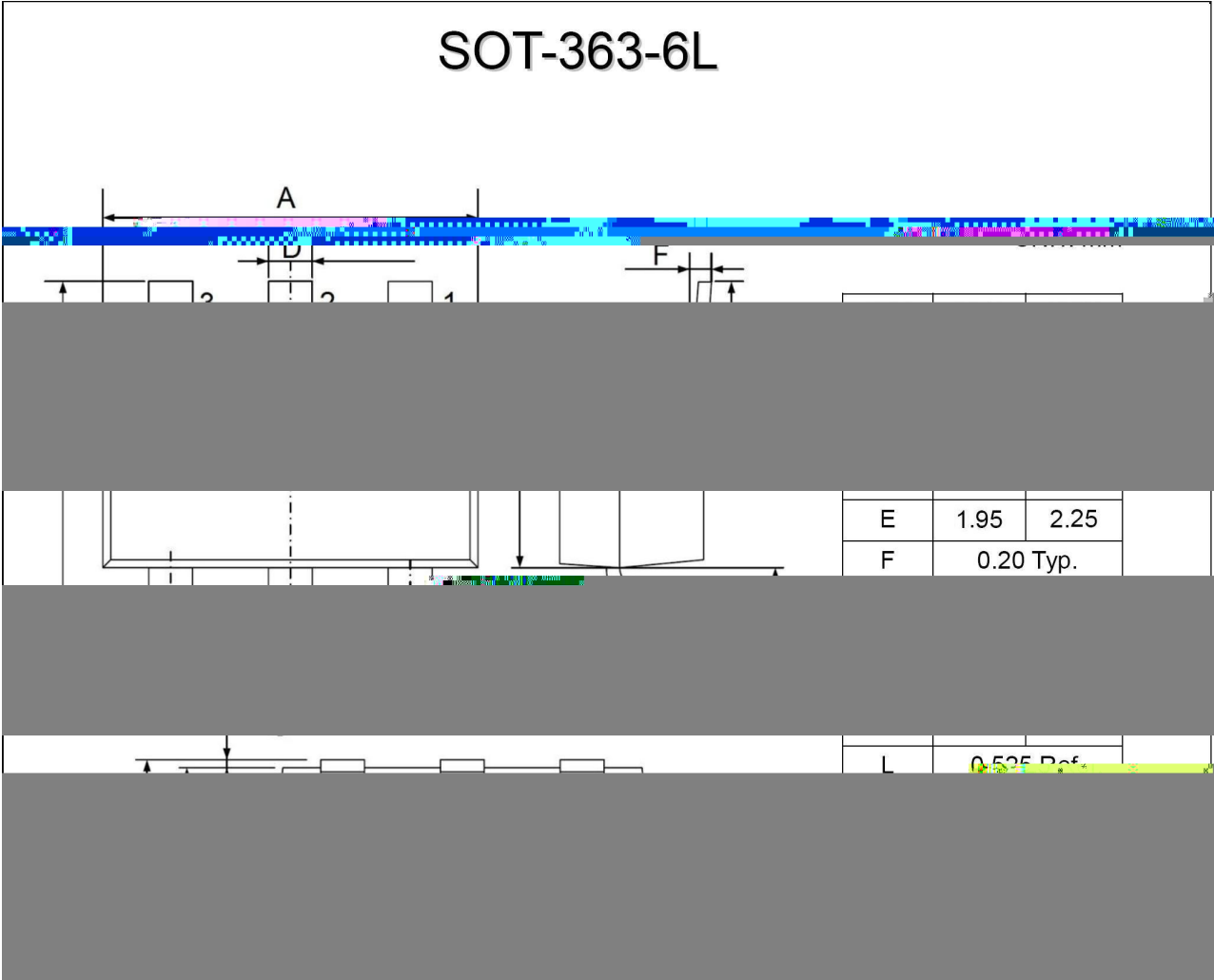
参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
		SD103ATW	
Peak Repetitive Peak Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	40	V
RMS Reverse Voltage	$V_{R(RMS)}$	2	V
Average Rectified Current	I_O	1	mA
Forward Continuons Current	I_{FM}	3 0	mA
Non-repetitive Peak Forward Surge Current $t \leq 10ms$	I_{FSM}	2	A
Power Dissipation	P_D	200	mW
Typical Thermal Resistance junction to Ambient	R_{JA}	00	$^{\circ}C/W$
unction temperature	T_J	12	$^{\circ}C$
unction and Storage Temperature Range	T_{ST}	- ~ 12	$^{\circ}C$

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Ma	单位 Unit
Reverse breakdown voltage	$V_{(BR)}$	$I_R = 100 \mu A$	40			V
Forward voltage	V_F	$I_F = 20mA$			0.3	V
		$I_F = 100mA$			0. 0	
Reverse current	I_R	$V_R = 10V$			2.0	A
		$V_R = 30V$			.0	
Capacitance between terminals	C_T	$V_R = 0V \quad f = 1.0MHz$		0		pF

SD103ATW

Rev.D Oct.-2021

/ Package Dimensions



SD103AT

() / **Temperature Profile for IR Reflow Soldering(Pb-Free)**

Note:

- | | | | |
|---|---------|-----------|--|
| 1 | 1 0 1 0 | 60 0sec; | 1.Preheating:1 0 1 0°C, Time:60 0sec. |
| 2 | 24 ± | ±0. sec; | 2.Peak Temp.:24 ± °C, Duration: ±0. sec. |
| 3 | 2 | 10°C/sec. | 3. Cooling Speed: 2 10°C/sec. |

/ **Resistance to Soldering Heat Test Conditions**

260± °C 10±1 sec.